

Description

The VSM5N06 uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Features

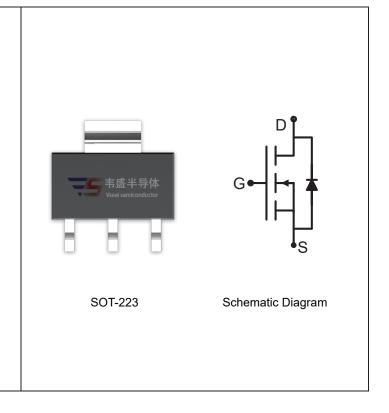
V_{DS} =60V,I_D =5A

 $R_{\text{DS(ON)}} < 55 \text{m}\Omega \text{ @ } V_{\text{GS}}\text{=}10 \text{V (Typ: }46 \text{m}\Omega)$

 $R_{DS(ON)} < 80 m\Omega @ V_{GS} = 4.5 V ~(Typ: 60 m\Omega)$

Application

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply



Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
VSM5N06-S23	VSM5N06	SOT-223	Ø330mm	12mm	2500 units

Absolute Maximum Ratings (T_A=25 ℃ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	60	V
Gate-Source Voltage	Vgs	±20	V
Drain Current-Continuous	I _D	5	А
Drain Current-Continuous(T _C =100°C)	I _D (100℃)	3.5	Α
Pulsed Drain Current	I _{DM}	20	А
Maximum Power Dissipation	P _D	2	W
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55 To 150	$^{\circ}$ C

Thermal Characteristic

Thermal Resistance,Junction-to-Ambient ^(Note 2)	$R_{\theta JA}$	62.5	°C/W
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Electrical Characteristics (T_A=25 ℃ unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit		
Off Characteristics								
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	60	69	-	V		
Zero Gate Voltage Drain Current	I _{DSS}	V_{DS} =60V, V_{GS} =0V	-	-	1	μΑ		



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Gate-Body Leakage Current	I _{GSS}	V_{GS} =±20 V , V_{DS} =0 V	-	-	±100	nA
On Characteristics (Note 3)	<u> </u>		•			
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS},I_{D}=250\mu A$	1.2	2	2.5	V
Drain-Source On-State Resistance	В	V_{GS} =10V, I_D =4.5A		46	55	
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =4.5V, I _D =4A		60	80	
Forward Transconductance	g FS	V _{DS} =5V,I _D =4.5A	11	-	-	S
Dynamic Characteristics (Note4)	·				•	
Input Capacitance	C _{lss}	V _{DS} =25V,V _{GS} =0V, F=1.0MHz		450		PF
Output Capacitance	Coss			60		PF
Reverse Transfer Capacitance	C _{rss}	F-1.0WII IZ		25		PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}		-	4.7	-	nS
Turn-on Rise Time	t _r	V_{Ds} =30 V , I_{D} =4.5 A	-	2.3	-	nS
Turn-Off Delay Time	$t_{d(off)}$	V_{GS} =10 V , R_{GEN} =3 Ω	-	15.7	-	nS
Turn-Off Fall Time	t _f		-	1.9	-	nS
Total Gate Charge	Q_g	\/ -20\/ -4.54	-	8.5	-	nC
Gate-Source Charge	Q _{gs}	$V_{DS}=30V,I_{D}=4.5A,$ $V_{GS}=10V$	-	1.6	-	nC
Gate-Drain Charge	Q_{gd}	VGS-10V	-	2.2	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =5A	-	-	1.2	V
Diode Forward Current (Note 2)	I _S		-	-	5	Α

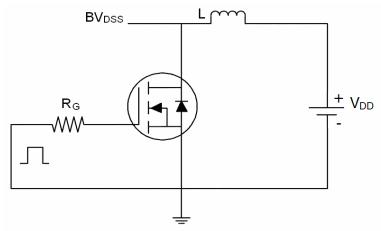
Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- **4.** Guaranteed by design, not subject to production

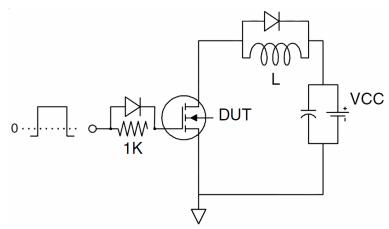


Test Circuit

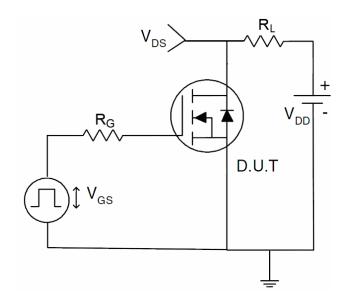
1) E_{AS} Test Circuit



2) Gate Charge Test Circuit



3) Switch Time Test Circuit





Typical Electrical and Thermal Characteristics (Curves)

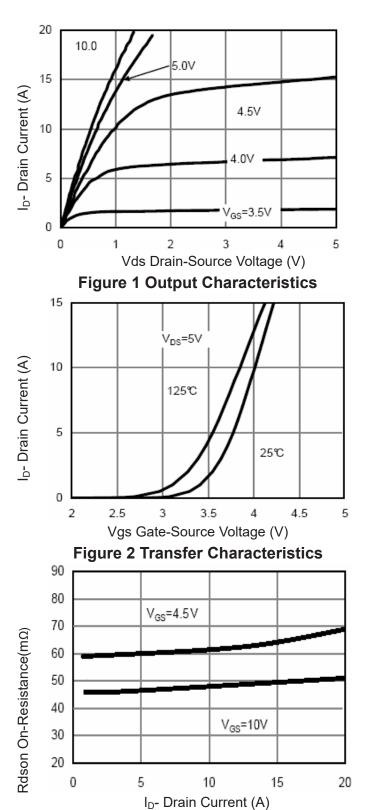


Figure 3 Rdson- Drain Current

I_D=4.5A Normalized On-Resistance 2.0 1.0 0.0 60 80 T_J-Junction Temperature(°ℂ) **Figure 4 Rdson-Junction Temperature** 10 Vgs Gate-Source Voltage (V) 8 6 4 2 0 0 10 Qg Gate Charge (nC) Figure 5 Gate Charge 1.0E+01

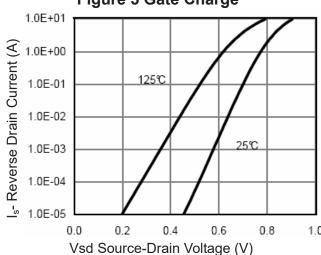


Figure 6 Source- Drain Diode Forward



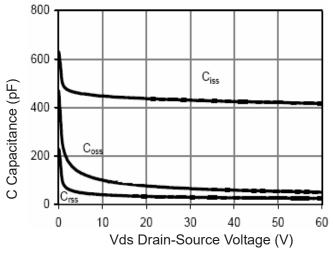


Figure 7 Capacitance vs Vds

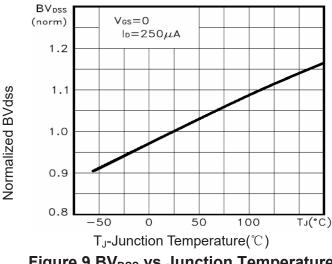


Figure 9 BV_{DSS} vs Junction Temperature

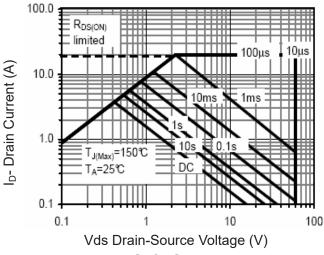


Figure 8 Safe Operation Area

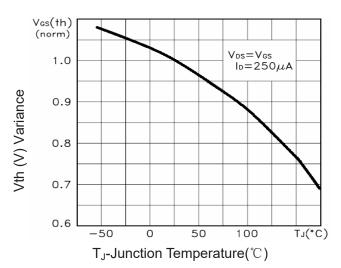


Figure 10 V_{GS(th)} vs Junction Temperature

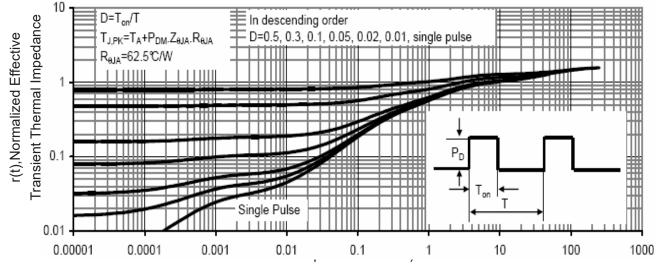


Figure 11 Normalized Maximum Transient Thermal Impedance